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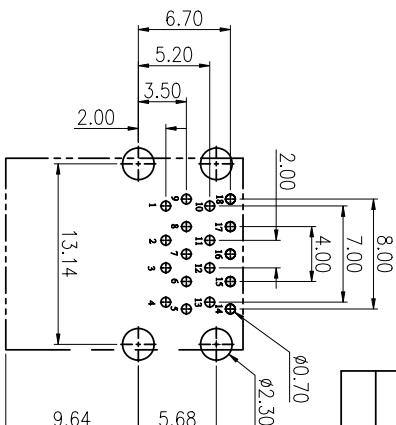
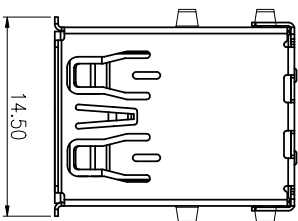
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MAPX

MODIFICATION

DRW

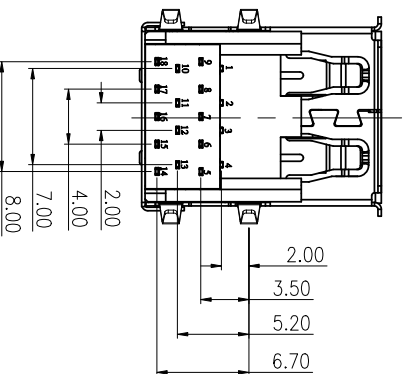
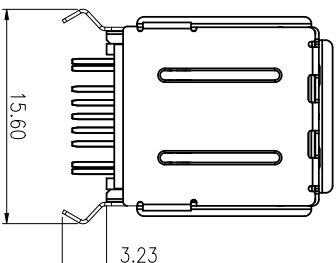
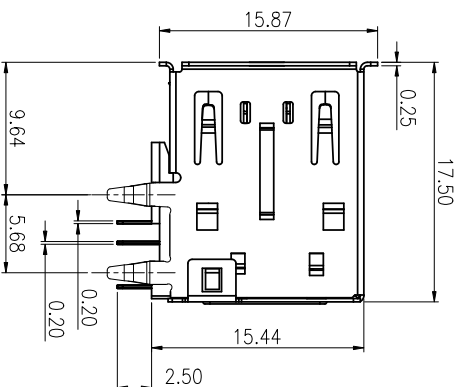
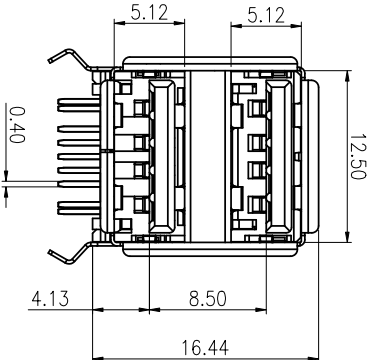
DATE



RECOMMENDED P.C.B HOLE LAYOUT
TOP VIEW(TOLERANCE:±0.05)

NOTE:
A. MATERIAL:
1. HOUSING: PBT/PA66/PA9T
2. COVER: PBT/PA66/PA9T
3. CONTACT: COPPER ALLOY
4. SHELL: SUS201
5. MIDDLE SPRING: SUS201

B. PLATING:
1. CONTACT: CONTACT AREA GOLD PLATED
SOLDER AREA TIN(80u"MIN) PLATED
UNDER PLATED NICKEL(30u"MIN)
2. SHELL: NICKEL(40u"MIN) PLATED



产品图

深圳市精拓金电子有限公司
Shenzhen Jing Tuo Jin Electronics Co., Ltd.

公差一览表

TOLERANCE UNLESS OTHERWISE

单位	MM	制图	审核	日期	2021-03-10	核准	黄国荣	角法	VER	AO
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比例	1:1	日期	2021-03-10	核准	黄国荣	角法	VER	AO
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日期	2021-03-10	核准	黄国荣	角法	VER	AO
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